APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

1. (Amended) A method for packaging a microelectronic substrate, comprising:

positioning a conductive member at least proximate to the microelectronic substrate, the conductive member having first and second neighboring conductive portions with at least part of the first conductive portion separated from the neighboring second conductive portion to define an intermediate region between the conductive portions;

electrically coupling the first conductive portion of the conductive member to a first coupling site of the microelectronic substrate and electrically coupling the second conductive portion of the conductive member to a second coupling site of the microelectronic substrate; and

providing a dielectric material in the intermediate region between the conductive portions, the dielectric material including argon and/or helium~~having a dielectric constant less than about 3.5~~.

14. (Amended) The method of claim ~~13~~16, further comprising selecting the dielectric material to have a dielectric constant of from about 1.0 to about 2.0.

16. (Twice amended) ~~The method of claim 13, further comprising~~ A method for processing a circuit board for coupling to a microelectronic substrate, comprising:

providing a circuit board having a first conductive trace with a portion spaced apart from a corresponding portion of a second conductive trace to define an intermediate region between the first and second conductive traces;

disposing in the intermediate region between the conductive traces a dielectric material; and

selecting the dielectric material to include argon and/or helium.